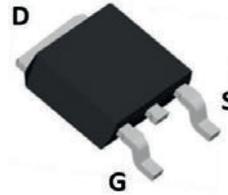
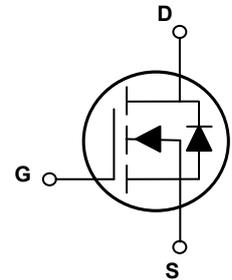


## Main Product Characteristics

$V_{(BR)DSS}$	150V
$R_{DS(ON)}$	52m $\Omega$ (Typ.)
$I_D$	20A



TO-252 (DPAK)



Schematic Diagram



## Features and Benefits

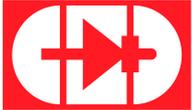
- Grand Turbo MOSFET process technology.
- Optimized the cell structure.
- Low on-resistance with low gate charge.
- Featuring low switching and drive losses.
- Fast switching and reverse body recovery.
- High ruggedness and robustness.

## Description

The GSFD68015 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{(BR)DSS}$	150	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ ) @ Steady-State <sup>1</sup>	$I_D$	20	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ ) @ Steady-State		14	
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	80	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	25	mJ
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	75	W
Linear Derating Factor ( $T_C=25^\circ\text{C}$ )		0.6	
Junction-to-Ambient (PCB Mounted, Steady-State) <sup>4</sup>	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$
Junction to Case	$R_{\theta JC}$	1.6	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 to +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150	$^\circ\text{C}$

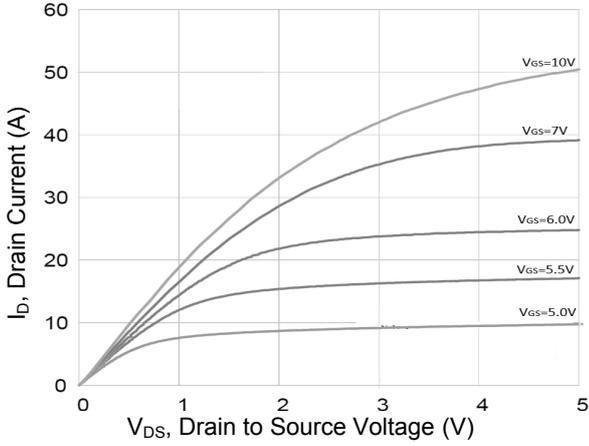

**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	150	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=150V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=125^\circ\text{C}$	-	-	50	$\mu A$
Gate-Source Forward Leakage	$I_{GSS}$	$V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=5A$	-	52	68	m $\Omega$
Gate Resistance	$R_g$	F=1MHz	-	2.5	-	$\Omega$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.1	3	3.9	V
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS}=75V, I_D=5A$ $V_{GS}=10V$	-	9.1	-	nC
Gate-Source Charge	$Q_{gs}$		-	3.5	-	
Gate-to-Drain("Miller") Charge	$Q_{gd}$		-	1.8	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DS}=30V, R_G=6\Omega,$ $V_{GS}=10V, I_D=5A$	-	7.3	-	nS
Rise Time	$t_r$		-	24	-	
Turn-Off Delay Time	$t_{d(off)}$		-	14	-	
Fall Time	$t_f$		-	22	-	
Input Capacitance	$C_{iss}$	$V_{DS}=75V, V_{GS}=0V,$ F=1MHz	-	518	-	pF
Output Capacitance	$C_{oss}$		-	76	-	
Reverse Transfer Capacitance	$C_{rss}$		-	3.3	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current (Body Diode)	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	20	A
Pulsed Source Current (Body Diode)	$I_{SM}$		-	-	80	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=2A$	-	1	1.2	V
Reverse Recovery Time	$t_{rr}$	$V_{GS}=0V, I_S=5A,$ $di/dt=100A/\mu s$	-	53	-	$\mu s$
Reverse Recovery Charge	$Q_{rr}$		-	0.11	-	nC

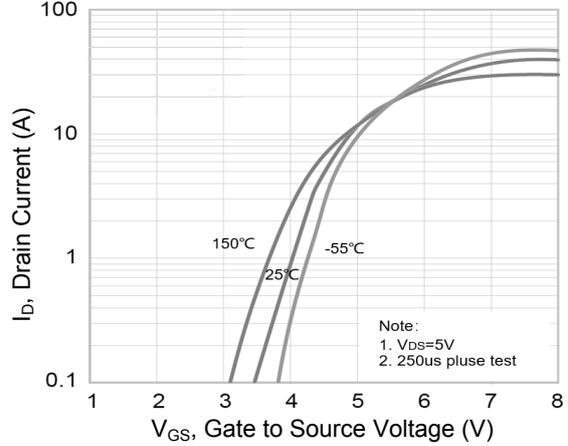
## Notes:

1. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
2. Repetitive rating; pulse width limited by max. junction temperature.
3. L=0.5mH,  $R_G=25\Omega$ ,  $V_{DD}=50V$ ,  $I_{AS}=10A, T_J=25^\circ\text{C}$ .
4. Device mounted on FR-4 PCB, 1inch x 0.85inch x 0.062 inch.

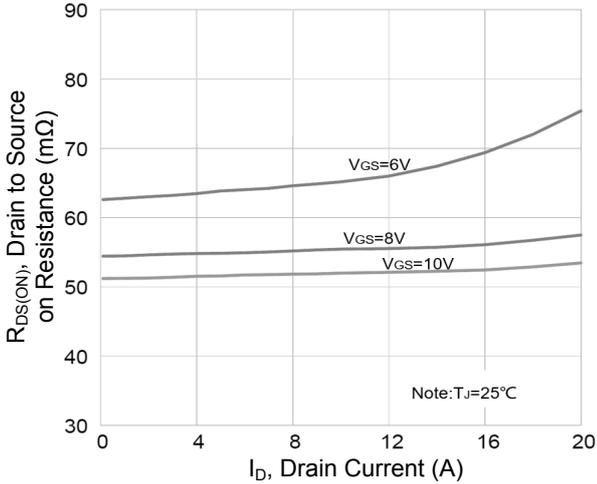
**Typical Electrical and Thermal Characteristic Curves**



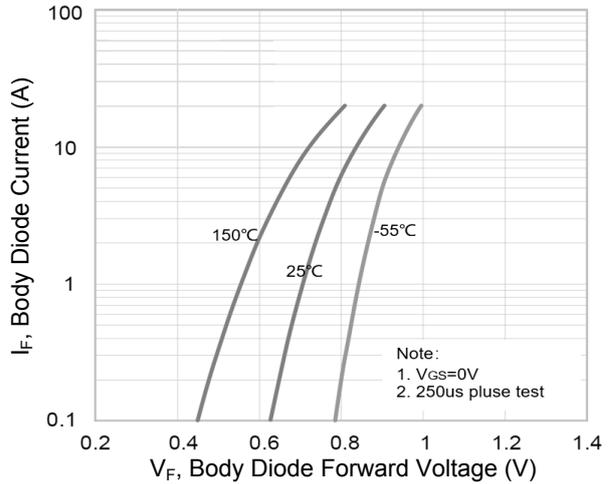
**Figure 1. Typical Output Characteristics**



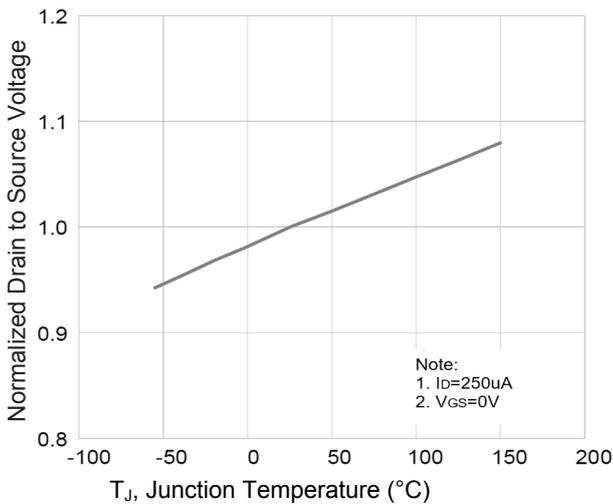
**Figure 2. Transfer Characteristics**



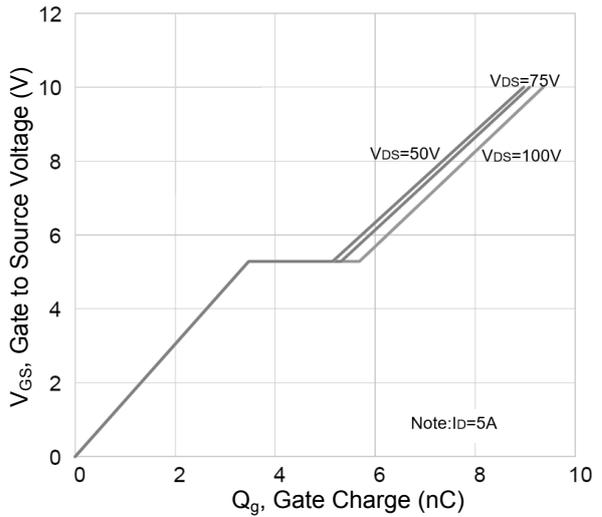
**Figure 3.  $R_{DS(ON)}$  vs. Drain Current**



**Figure 4. Body Diode Characteristics**

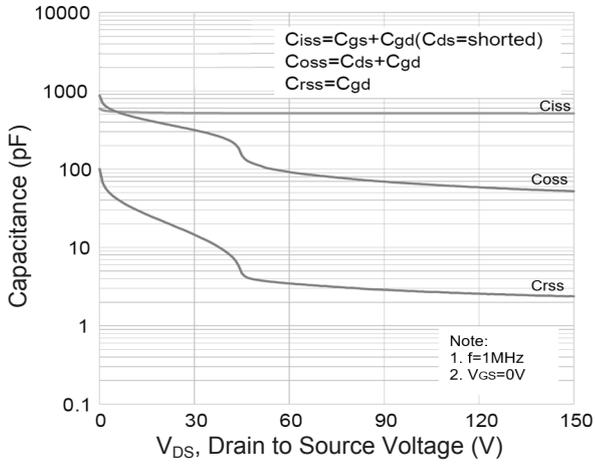


**Figure 5. Normalized  $BV_{DSS}$  vs.  $T_J$**

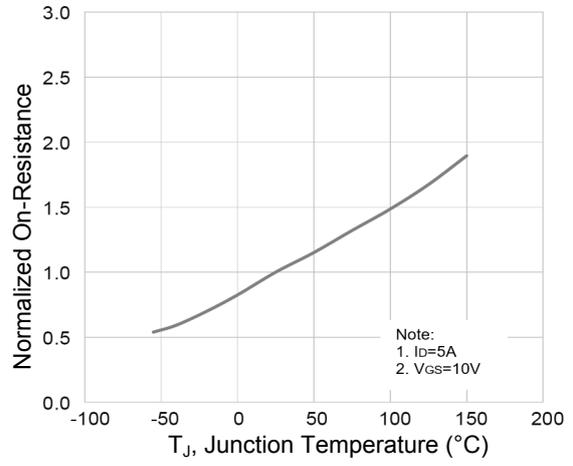


**Figure 6. Gate Charge Characteristics**

**Typical Electrical and Thermal Characteristic Curves**

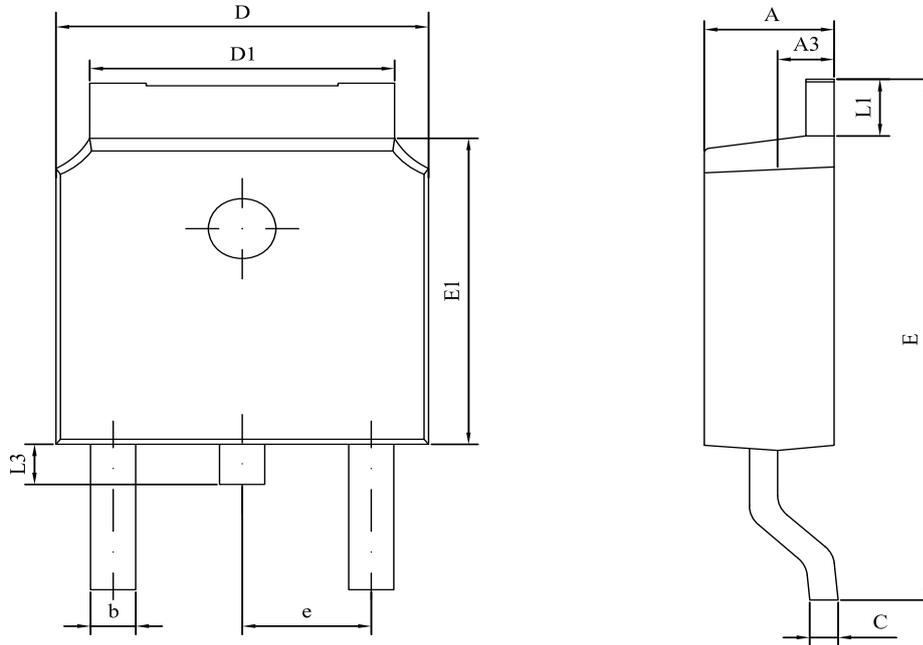


**Figure 7. Capacitance Characteristics**



**Figure 8. Normalized  $R_{DS(ON)}$  vs.  $T_J$**

### Package Outline Dimensions TO-252(DPAK)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.150	2.400	0.085	0.094
A3	0.900	1.100	0.035	0.043
b	0.500	0.900	0.020	0.035
C	0.400	0.650	0.016	0.026
D	6.300	6.900	0.248	0.272
D1	4.950	5.500	0.195	0.217
E	9.400	10.410	0.370	0.410
E1	5.900	6.300	0.232	0.248
e	2.286 BSC		0.090 BSC	
L1	0.890	1.270	0.035	0.050
L3	0.600	1.100	0.024	0.043

### Order Information

Device	Package	Marking	Carrier	Quantity
GSFD68015	TO-252(DPAK)	D68015	Tape & Reel	2,500 Pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)